

N-Channel 100-V (D-S) MOSFET

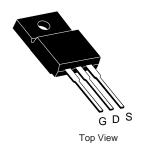
PRODUCT S	UMMARY	
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)
100	0.0085 at V _{GS} = 10 V	90
100	0.0100 at V _{GS} = 6 V	85

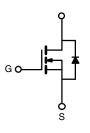
FEATURES

- TrenchFET® Power MOSFET
- 175 °C Maximum Junction Temperature
- Compliant to RoHS Directive 2002/95/EC









NI	Cha	nnal	M	SFET	_

ABSOLUTE MAXIMUM RATI	NGS $T_A = 25 ^{\circ}C$, unless other	wise noted		
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V _{DS}	100	V
Gate-Source Voltage		V _{GS}	± 20	V
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 25 °C	I_	90	
Continuous Diain Current (1) = 130 °C)	T _C = 125 °C	- I _D	70 ^a	A
Pulsed Drain Current		I _{DM}	287	A
Avalanche Current	L = 0.1 mH	I _{AS}	75	
Single Pulse Avalanche Energy ^b	L = 0.1 IIII	E _{AS}	280	mJ
	$T_C = 25$ °C (TO-220F)	P _D	56	W
Maximum Power Dissipation ^b	T _A = 25 °C (TO-220F)	J 'U	3.75	VV
Operating Junction and Storage Temperatu	ire Range	T _J , T _{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Limit	Unit	
Junction-to-Ambient	PCB Mount (TO-220) d	R _{thJA}	40		
Junction-to-Ambient	Free Air (TO-220)	' 'thJA	62.5	°C/W	
Junction-to-Case		R _{thJC}	0.6		

Notes

- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

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SPECIFICATIONS $T_J = 25$ °C	C, unless other	erwise noted					
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	·						
Drain-Source Breakdown Voltage	V _{DS}	V_{DS} $V_{GS} = 0 \text{ V, } I_{D} = 250 \mu\text{A}$				V	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1		3	ľ	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V _{DS} = 100 V, V _{GS} = 0 V			1	μA A Ω S PF	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V, T _J = 125 °C			50	μΑ	
		V _{DS} = 100 V, V _{GS} = 0 V, T _J = 175 °C			250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α	
		V _{GS} = 10 V, I _D = 30 A		0.0095			
	D	V _{GS} = 6 V, I _D = 20 A		0.0100			
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 30 A, T _J = 125 °C		0.0160		Ω	
		V _{GS} = 10 V, I _D = 30 A, T _J = 175 °C		0.0210			
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 30 A	25			S	
Dynamic ^b	<u> </u>						
Input Capacitance	C _{iss}			6550		pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		665			
Reverse Transfer Capacitance	C _{rss}			265			
Total Gate Charge ^c	Qg			105			
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 85 \text{ A}$		17		nC	
Gate-Drain Charge ^c	Q _{gd}			23			
Turn-On Delay Time ^c	t _{d(on)}			12	25		
Rise Time ^c	t _r	$V_{DD} = 50 \text{ V}, R_{L} = 0.6 \Omega$		90	135		
Turn-Off DelayTime ^c	t _{d(off)}	$I_D \cong 85 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		55	85	ns	
Fall Time ^c	t _f			130	195		
Source-Drain Diode Ratings and Cha	racteristics T _C	= 25 °C ^b					
Continuous Current	I _S			90			
Pulsed Current	I _{SM}			240		Α	
Forward Voltage ^a	V _{SD}	I _F = 85 A, V _{GS} = 0 V		1.0	1.5	V	
Reverse Recovery Time	t _{rr}			85	140	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = 50 A, dI/dt = 100 A/μs		4.5	7	Α	
Reverse Recovery Charge	Q _{rr}	1		0.17	0.35	μC	

Notes:

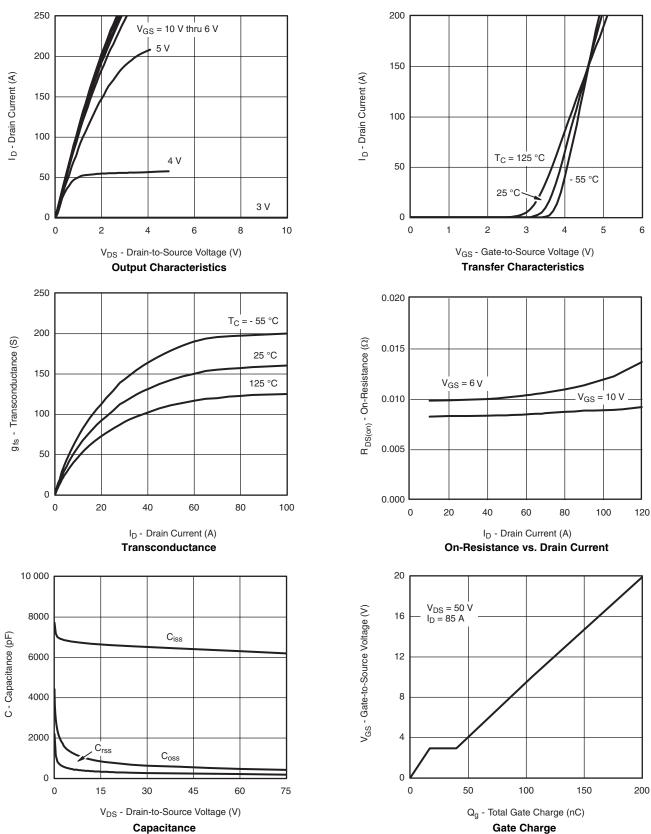
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- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



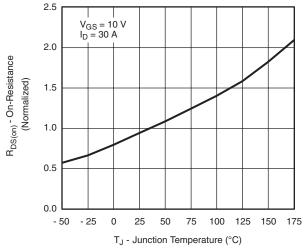
TYPICAL CHARACTERISTICS $T_A = 25 \, ^{\circ}C$, unless otherwise noted



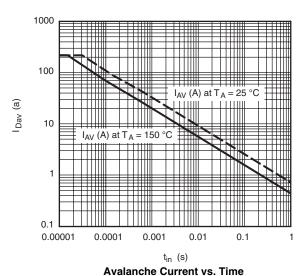
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TYPICAL CHARACTERISTICS $T_A = 25 \, ^{\circ}C$, unless otherwise noted

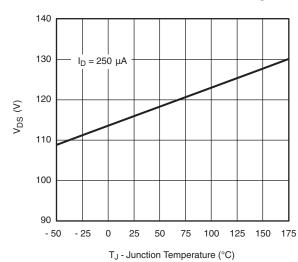


On-Resistance vs. Junction Temperature



T_J = 150 °C T_J = 25 °C T_J

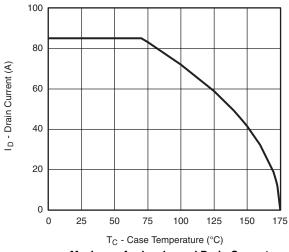
Source-Drain Diode Forward Voltage

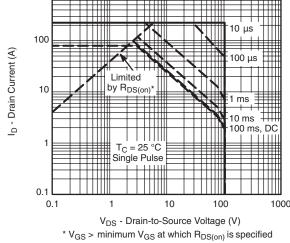


T_J - Drain-Source Breakdown vs. Junction-Temperature



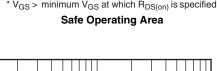
THERMAL RATINGS

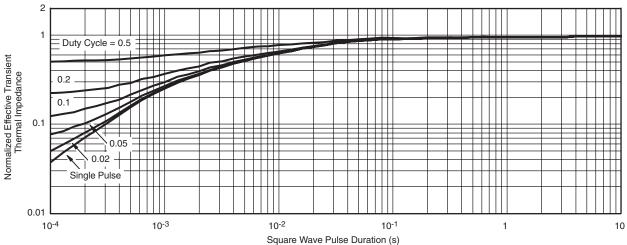




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Maximum Avalanche and Drain Current vs. Case Temperature

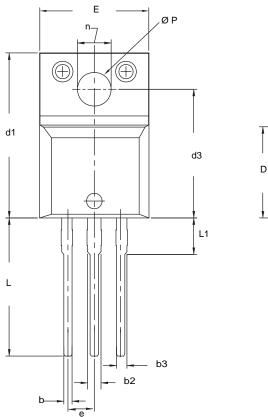


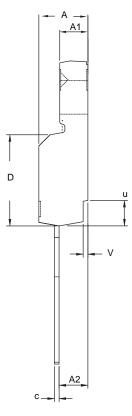


Normalized Thermal Transient Impedance, Junction-to-Case



TO-220 FULLPAK (HIGH VOLTAGE)





	MILLIMETERS		INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.570	4.830	0.180	0.190	
A1	2.570	2.830	0.101	0.111	
A2	2.510	2.850	0.099	0.112	
b	0.622	0.890	0.024	0.035	
b2	1.229	1.400	0.048	0.055	
b3	1.229	1.400	0.048	0.055	
С	0.440	0.629	0.017	0.025	
D	8.650	9.800	0.341	0.386	
d1	15.88	16.120	0.622	0.635	
d3	12.300	12.920	0.484	0.509	
Е	10.360	10.630	0.408	0.419	
е	2.54	BSC	0.100 BSC		
L	13.200	13.730	0.520	0.541	
L1	3.100	3.500	0.122	0.138	
n	6.050	6.150	0.238	0.242	
ØΡ	3.050	3.450	0.120	0.136	
u	2.400	2.500	0.094	0.098	
V	0.400	0.500	0.016	0.020	

DWG: 5972

Notes

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- To be used only for process drawing.
 These dimensions apply to all TO-220, FULLPAK leadframe versions 3 leads.
 All critical dimensions should C meet C_{pk} > 1.33.
 All dimensions include burrs and plating thickness.
 No chipping or package damage.



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